

ServerWorks ServerSet™ III WS

Product Overview

Features	Benefits
133 MHz Front Side Bus capability	<ul style="list-style-type: none"> • Supports 133 MHz system bus for single and dual processor configurations • Significantly increases bandwidth available for multiprocessor Workstations
PC133 SDRAM technology	<ul style="list-style-type: none"> • Superior memory performance in terms of higher bandwidth and lower access latency • Increases flexibility of system design for memory configurations • Proven technology with low cost structure
Workstation Optimized Memory Technology (Up to 8-GBytes)	<ul style="list-style-type: none"> • High Bandwidth 2-way interleaved architecture achieves up to 2.1 GBytes/s • Advanced ECC algorithms that maintain system data integrity • Supports a large capacity of memory up to 8-GBytes • Supports wide range of memory DIMMs including 64, 128, 256, 512-MByte, and 1-GByte.
Advanced “Inter Module Bus” (IMB) Technology	<ul style="list-style-type: none"> • Supports 1 GByte/s operation and low latency IO transactions on full duplex, point to point, source synchronous bus • Defined Interconnect from North Bridge to remote PCI IO Bridges
Advanced 64-bit PCI Technology	<ul style="list-style-type: none"> • Two full independent 64-bit PCI Buses • Maximizes IO bandwidth for the next generation of 64-bit PCI cards • Supports up to 2 full 64-bit/66 MHz PCI busses • Supports up to 5 64-bit/33 MHz PCI busses
Advanced IO Caching Technology	<ul style="list-style-type: none"> • Increases sustainable PCI bus bandwidth by off loading system resources • Reduces Front Side bus snoop traffic for enhanced multiprocessing performance
AGP 4X Technology	<ul style="list-style-type: none"> • Allows the highest graphics performance currently available • Significant increase in bandwidth (2x) to support 3D graphics
Scalable Architecture	<ul style="list-style-type: none"> • Increases flexibility of system design for processor, memory, and PCI configurations • Strong architectural foundation that enables a smooth transition to the next generation of server technology (i.e. PCI-X, DDR)
Full Peer-to-Peer Support	<ul style="list-style-type: none"> • Allows full peer-to-peer transactions between PCI busses • Increases options for Intelligent IO and Server Management cards
Integrated IOAPIC	<ul style="list-style-type: none"> • Removes the need for a separate IOAPIC chip • BOM cost savings, additional board real estate, and increased

	design flexibility
ATA66	<ul style="list-style-type: none"> Enhances HDD access for faster reads and writes
4 USB Ports	<ul style="list-style-type: none"> Provides the end user with more options to connect peripherals
ServerSet™ III WS Components:	Package:
NB6536 North Bridge 2.0HE	<ul style="list-style-type: none"> 644 Tape Ball Grid Array (TBGA)
NB6566 South Bridge	<ul style="list-style-type: none"> 352 Plastic Ball Grid Array (PBGA)
NB6555-AGP IO Bridge 2.0	<ul style="list-style-type: none"> 352 Plastic Ball Grid Array (PBGA)
NB6525 Memory Address Data Path (MADP)	<ul style="list-style-type: none"> 256 Plastic Ball Grid Array (PBGA)

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